

Technical Data Sheet

DOWSIL™ TC-5625C Thermally Conductive Compound

Greenish yellow, flowable, non-curing thermally conductive compound

Features & Benefits

- Optimized polymer matrix to help reduce pump out
- Flowable
- Good thermal conductivity
- Low thermal resistance
- Non-curing, no need for curing ovens
- Heat dissipation from circuitry components
- Can achieve thin Bond Line Thickness (BLT)

Composition

Filled polydimethysiloxane

Applications

• DOWSIL™ TC-5625C Thermally Conductive Compound is suitable for use as an interface material for a variety of mid to high end lamps and luminaires.

Typical Properties

Specification Writers: These values are not intended for use in preparing specifications.

Property	Unit	Result
One-part or Two-part		One
Color		Greenish yellow
CTM 0050 Viscosity	Pa-sec	77.0
	cР	77,000
Thixotropy		1.64
Specific Gravity (Uncured)		4.2
Non-Volatile Content (NVC)	%	99.93
Thermal Conductivity	W/m-K	2.7
Thermal Resistance at 40 psi	°C-cm ² /W	0.09
CTM 0114 Dielectric Strength	kV/mm	1.89
	Volts/mil	47.3
Volume Resistivity	ohm*cm	1.3E+13
Dielectric Constant @ 1 kHz		14.0
Dissipation Factor @ 1 kHz		0.073
	One-part or Two-part Color Viscosity Thixotropy Specific Gravity (Uncured) Non-Volatile Content (NVC) Thermal Conductivity Thermal Resistance at 40 psi Dielectric Strength Volume Resistivity Dielectric Constant @ 1 kHz	One-part or Two-part Color Viscosity Pa-sec cP Thixotropy Specific Gravity (Uncured) Non-Volatile Content (NVC) % Thermal Conductivity W/m-K Thermal Resistance at 40 psi °C-cm²/W Dielectric Strength kV/mm Volts/mil Volume Resistivity ohm*cm

^{1.} CTM: Corporate Test Method, copies of CTM's are available on request.

Form No. 11-3662-01-0320 S2D

Description

Dow thermally conductive compounds are grease like silicone materials, heavily filled with heat-conductive metal oxides. This combination promotes high thermal conductivity, low bleed and high-temperature stability. The compounds are designed to maintain a positive heat sink seal to improve heat transfer from the electrical device or PCB system assembly to the heat sink or chassis, thereby increasing the overall efficiency of the device. PCB systems assembly devices are continually designed to deliver higher performance. Especially in the area of consumer devices, there is also a continual trend towards smaller, more compact designs. In combination these factors typically mean that more heat is generated in the device. Thermal management of PCB system assemblies is a primary concern of design engineers. A cooler device allows for more efficient operation and better reliability over the life of the device. As such, thermally conductive compounds play an integral role here. Thermally conductive materials act as a thermal "bridge" to remove heat from a heat source (device) to the ambient via a heat transfer media (i.e. heat sink). These materials have properties such as low thermal resistance, high thermal conductivity, and can achieve thin Bond Line Thicknesses (BLTs) which can help to improve the transfer of heat away from the device.

Application Methods

- Screen print
- Stencil print
- Dispense

Solvent Exposure

In general, the product is resistant to minimal or intermittent solvent exposure, however best practice is to avoid solvent exposure altogether.

Handling Precautions

PRODUCT SAFETY INFORMATION REQUIRED FOR SAFE USE IS NOT INCLUDED IN THIS DOCUMENT. BEFORE HANDLING, READ PRODUCT AND SAFETY DATA SHEETS AND CONTAINER LABELS FOR SAFE USE, PHYSICAL AND HEALTH HAZARD INFORMATION. THE SAFETY DATA SHEET IS AVAILABLE ON THE DOW WEBSITE AT DOW.COM, OR FROM YOUR DOW SALES APPLICATION ENGINEER, OR DISTRIBUTOR, OR BY CALLING DOW CUSTOMER SERVICE.

Usable Life and Storage

The product should be stored in its original packaging with the cover tightly attached to avoid any contamination. Store in accordance with any special instructions listed on the product label. The product should be used by the indicated Exp. Date found on the label.

Limitations

This product is neither tested nor represented as suitable for medical or pharmaceutical uses.

Health and Environmental Information

To support customers in their product safety needs, Dow has an extensive Product Stewardship organization and a team of product safety and regulatory compliance specialists available in each area.

For further information, please see our website, dow.com or consult your local Dow representative.

Form No. 11-3662-01-0320 S2D

Disposal Considerations

Dispose in accordance with all local, state (provincial) and federal regulations. Empty containers may contain hazardous residues. This material and its container must be disposed in a safe and legal manner.

It is the user's responsibility to verify that treatment and disposal procedures comply with local, state (provincial) and federal regulations. Contact your Dow Technical Representative for more information.

Product Stewardship

Dow has a fundamental concern for all who make, distribute, and use its products, and for the environment in which we live. This concern is the basis for our product stewardship philosophy by which we assess the safety, health, and environmental information on our products and then take appropriate steps to protect employee and public health and our environment. The success of our product stewardship program rests with each and every individual involved with Dow products - from the initial concept and research, to manufacture, use, sale, disposal, and recycle of each product.

Customer Notice

Dow strongly encourages its customers to review both their manufacturing processes and their applications of Dow products from the standpoint of human health and environmental quality to ensure that Dow products are not used in ways for which they are not intended or tested. Dow personnel are available to answer your questions and to provide reasonable technical support. Dow product literature, including safety data sheets, should be consulted prior to use of Dow products. Current safety data sheets are available from Dow.

How Can We Help You Today?

Tell us about your performance, design, and manufacturing challenges. Let us put our silicon-based materials expertise, application knowledge, and processing experience to work for you.

For more information about our materials and capabilities, visit dow.com.

To discuss how we could work together to meet your specific needs, go to **dow.com** for a contact close to your location. Dow has customer service teams, science and technology centers, application support teams, sales offices, and manufacturing sites around the globe.

dow.com

NOTICE: No freedom from infringement of any patent owned by Dow or others is to be inferred. Because use conditions and applicable laws may differ from one location to another and may change with time, Customer is responsible for determining whether products and the information in this document are appropriate for Customer's use and for ensuring that Customer's workplace and disposal practices are in compliance with applicable laws and other government enactments. The product shown in this literature may not be available for sale and/or available in all geographies where Dow is represented. The claims made may not have been approved for use in all countries. Dow assumes no obligation or liability for the information in this document. References to "Dow" or the "Company" mean the Dow legal entity selling the products to Customer unless otherwise expressly noted. NO WARRANTIES ARE GIVEN; ALL IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE ARE EXPRESSLY EXCLUDED.

